



Material Content Data Sheet



Sales Product Name		BSC0500NSI		Issued		20. July 2018		
MA#		MA001301104						
Package		PG-TDSON-8-6		Weight*		107.12 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.629	0.59	0.59	5873	5873
leadframe	non noble metal	iron	7439-89-6	0.038	0.04		353	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		106	
	non noble metal	copper	7440-50-8	37.762	35.25	35.30	352518	352977
wire	non noble metal	copper	7440-50-8	0.021	0.02	0.02	194	194
encapsulation	organic material	carbon black	1333-86-4	0.088	0.08		817	
	plastics	epoxy resin	-	6.215	5.80		58018	
	inorganic material	silicondioxide	60676-86-0	37.464	34.97	40.85	349740	408575
leadfinish	non noble metal	tin	7440-31-5	1.470	1.37	1.37	13721	13721
plating	noble metal	silver	7440-22-4	0.166	0.15	0.15	1545	1545
solder	noble metal	silver	7440-22-4	0.023	0.02		219	
	non noble metal	tin	7440-31-5	0.019	0.02		175	
	non noble metal	lead	7439-92-1	0.895	0.84	0.88	8351	8745
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		208	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		63	
	non noble metal	copper	7440-50-8	22.292	20.81	20.84	208099	208370
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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